Authorized Representative*  Title - Representative  Phone - Representative*  Email - Representative*	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.						
Company name* Company unique ID  Unique ID Authority  Response Date*  2024-09-26  Contact Name  Title - Contact  Product Envisewards Authorized Representative* Product Enviro Compliance Authorized Representative*  Product Enviro Compliance Authorized Representativ							
nsemi ontact Name Title - Contact Product-Env-Stewards Product-Env-Stewards Title - Representative Title - Representative Product-Env-Stewards Product-Env-S							
Title - Contact Name Product Env-Stewards Product	Response Date*						
Product-Env-Stewards uthorized Representative* Title - Representative Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards@onsemi.com NA Nanufacturing Site Weight* UOM NA	2024-09-26						
Title - Representative Product Enviro Compliance NA Product-Env-Stewards Product Enviro Compliance NA Product-Env-Stewards © onsemi.com Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM MC78M05ABTG ANA 500MA 5V VREG 2024-09-26 MY1 1365.61 mg  Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3	Email - Contact*						
Product-Env-Stewards  Requester Item Number  Mfr Item Number  Mfr Item Name  Effective Date  Version  Manufacturing Site  Weight*  UOM  MC78M05ABTG  ANA 500MA 5V VREG  2024-09-26  MY1  1365.61  mg  Manufacturing Proccess Information  Terminal Plating / Grid Array Material  Terminal Base Alloy  Matte Tin (Sn) - annealed  CU Alloy  NA  Product-Env-Stewards@onsemi.com  Manufacturing Site  Weight*  UOM  MY1  1365.61  mg  Peak Process Body Temperature  Max Time at Peak Temperature  Number of Reflow Cycles  Na  O  C  30  Seconds  3	Product-Env-Stewards@onsemi.com						
Requester Item Number Mfr Item Number Mfr Item Name Effective Date Version Manufacturing Site Weight* UOM  MC78M05ABTG ANA 500MA 5V VREG 2024-09-26 MY1 1365.61 mg  Manufacturing Proccess Information  Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3	Email - Representative*						
MC78M05ABTG ANA 500MA 5V VREG 2024-09-26 MY1 1365.61 mg    Internation	Product-Env-Stewards@onsemi.com						
Terminal Plating / Grid Array Material   Terminal Base Alloy   J-STD-020 MSL Rating   Peak Process Body Temperature   Max Time at Peak Temperature   Number of Reflow Cycles   Matte Tin (Sn) - annealed   CU Alloy   NA   0   C   30   seconds   3	Unit Type						
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3	Each						
Matte Tin (Sn) - annealed CU Alloy NA 0 C 30 seconds 3							
Patter III (bi) dimensed Co IIIo) 1142   0   C   D0   Seconds   D	<u> </u>						
omments							
or more information regarding material composition please refer to page 3							

RoHS Material Composition Declaration			Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP).								
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.									
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.									
Supplier Digital Signature Ra	astislav Drska	-En							

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.61	mg	Supplier	Silicon (Si)	7440-21-3		1.61	mg
Die Attach	0.21	mg	A	Lead (Pb)	7439-92-1	7a	0.1995	mg
			Supplier	Tin (Sn)	7440-31-5		0.0105	mg
Lead Frame	677.24		В	Nickel (Ni)	7440-02-0		0.3386	mg
			Supplier	Iron (Fe)	7439-89-6		0.6772	mg
			Supplier	Copper (Cu)	7440-50-8		676.0209	mg
			Supplier	Phosphorus (P)	7723-14-0		0.2032	mg
Mold Compound-Black	644.0	mg		Phenolic Resin	proprietary data		38.64	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		64.4	mg
			Supplier	Carbon Black (C)	1333-86-4		3.22	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		48.3	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		489.44	mg
Plating	42.4	mg	Supplier	Tin (Sn)	7440-31-5		42.4	mg
Wire Bond - Cu	0.15	mg	Supplier	Copper (Cu)	7440-50-8		0.15	mg